



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-07
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	BZZM*B6LA82R	A	BO2A	2016-01-07
Amount	UoM	Unit type	ST ECOPACK Grade	
80	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ating is used or other bulk terminati	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package: 07 SO 08 .15 JEDEC;MDF valid for M41T82RM6F			

QueryList : ROHS directive 2011/65/EU _ July 2011

Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false

Exemption Id.	Description

QueryList : REACH-17th December 2015

Query	Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BZZM*86LA82R					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.763	mg	supplier	die	Silicon (Si)	7440-21-3		3.676	mg	976880	45950
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	4783	225
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	2126	100
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	531	25
				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.010	mg	2657	125
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.049	mg	13022	613
Leadframe	Copper & its alloys	31.638	mg	supplier	alloy	Copper (Cu)	7440-50-8		30.755	mg	972091	384438
				supplier	alloy	Iron (Fe)	7439-89-6		0.723	mg	22852	9038
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.044	mg	1391	550
				supplier	alloy	Zinc (Zn)	7440-66-6		0.038	mg	1201	475
				supplier	metallization	Nickel (Ni)	7440-02-0		0.071	mg	2244	888
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	158	63
				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	63	25
				supplier	metallization	Silver (Ag)	7440-22-4		0.721	mg	749480	9013
Die attach	Other Organic Materials	0.962	mg	supplier	glue	Epoxy Cresol Novolak	29690-82-2		0.237	mg	246362	2963
				supplier	glue	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.004	mg	4158	50
				supplier	wire	Gold (Au)	7440-57-5		0.077	mg	1000000	963
Bonding wire	Precious metals	0.077	mg	supplier	wire	Gold (Au)	7440-57-5		0.077	mg	1000000	963
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		4.313	mg	99013	53913
				supplier	mold compound	phenol resin	9003-35-4		2.156	mg	49495	26950
				supplier	mold compound	Carbon Black	1333-86-4		0.431	mg	9894	5388
				supplier	mold compound	Silica, vitreous	60676-86-0		34.503	mg	792080	431288
				supplier	mold compound	Antimony Trioxide	1309-64-4		0.863	mg	19812	10788
encapsulation	Other Organic Materials	43.560	mg	supplier	mold compound	Brominated epoxy resin	40039-93-8		0.863	mg	19812	10788
				supplier	mold compound	additive	Proprietary		0.431	mg	9894	5388